技术数据表

# 血氧感测二极管

## 特点（C ）：

L/W/H :6.0*4.8*1.1mm

Outline Dimensions (L / w / h): 6.0*4.8*1.1 mm

: /

Luminous color and colloid: Infrared reception/black colloid

ROHS

Environmental protection products Complied With RoHS Directive

EIA

EIA standard packaging

Suitable for SMT automatic mounter

Suitable for reflow soldering production

Compatible With SMT Automatic Equipment

## 应用领域（ ）：

Security monitoring

Iris Recognition

Temperature detection sensing circuit

Remote sensing

Oximeter

Infrared scanning

# 目录

电性参数

典型特性曲线

可靠性实验

外形尺寸

# 电性参数

**极限参数** =25 **:**
Absolute Maximum Ratings

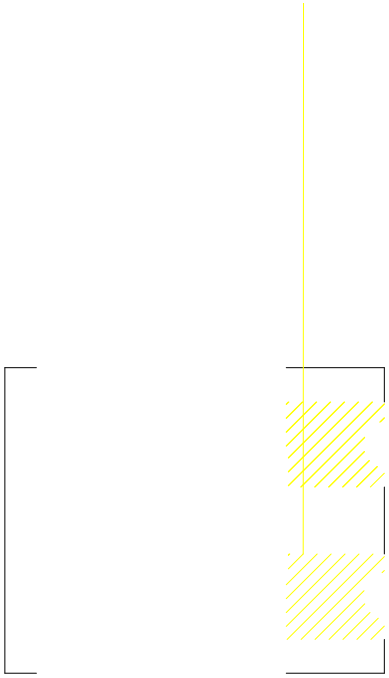
| | | | |
|---|---|---|---|
| Power consumption | Pd | 130 | mW |
| Reverse voltage | VR | 15 | **V** |
| Operating ambient temperature | Topr | -30 C ~ + 8 C | |
| Storage ambient temperature | Tstg | -40 C ~ + C | |
| Welding conditions | Tsol | Reflow soldering : 260 C s<br>Manual welding : 300 C 3s | |

* 0.1ms 1/10

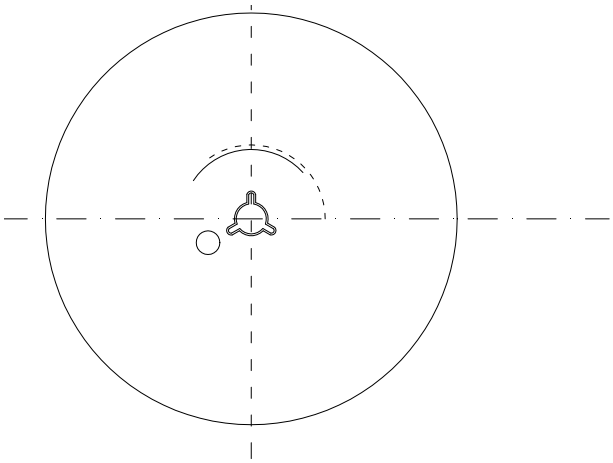
* Note: Pulse width 0.1ms, Duty 1/10

## 可靠性试验

## 外形尺寸



## 包装（ ）



Notes: 1. All dimensions are in millimeters ;

Tolerance is ± 0.10 mm unless otherwise noted.

Part No.:XL-6048PBC-2P

300

# 焊接指导（ ）

[redacted]

30 3 50 30

LED

300W LED

LED

It is recommended that alcohol be used as a solvent for cleaning after soldering. Cleaning is to go under 30 for 3 minutes or 50 for 30 seconds. When using other solvents, it should be confirmed beforehand whether the solvents will dissolve the package and the resin or not.

Ultrasonic cleaning is also an effective way for cleaning. But the influence of Ultrasonic cleaning on LED depends on factors such as ultrasonic power. Generally, the ultrasonic power should not be higher than 300W. Before cleaning, a pretest should be done to confirm whether any damage to LEDs will occur.

* **注意：** PCB

* This general guideline may not apply to all PCB designs and configurations of all soldering equipment. The technics in practise is influenced by many factors, it should be specialized base on the PCB designs and configurations of the soldering equipment..

## 使用注意事项（ ）

**贮存：**

Moisture proof and anti-electrostatic package with moisture absorbent material is used, to keep moisture to a minimum.

30 60%RH

Before opening the package, the product should be kept at 30 or less and humidity less than 60% RH, and be used within a year.

30 10%RH 168 7

30 60%RH

After opening the package, the product should be stored at 30 or less and humidity less than 10%RH, and

LED

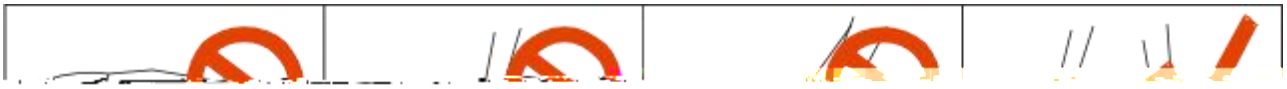
LED B

LED $V_F$ LED

## 使用注意事项（ ）

**其他事项：**

When handling the product, touching the encapsulant with bare hands will not only contaminate its surface, but also affect on its optical characteristics. Excessive force to the encapsulant might result in catastrophic failure of the LEDs due to die breakage or wire deformation. For this reason, please do not put excessive stress on LEDs, especially when the LEDs are heated such as during Reflow Soldering.



LED

The epoxy resin of encapsulant is fragile, so please avoid scratch or friction over the epoxy resin surface. While handling the product with tweezers, do not